



SMTHDTxx

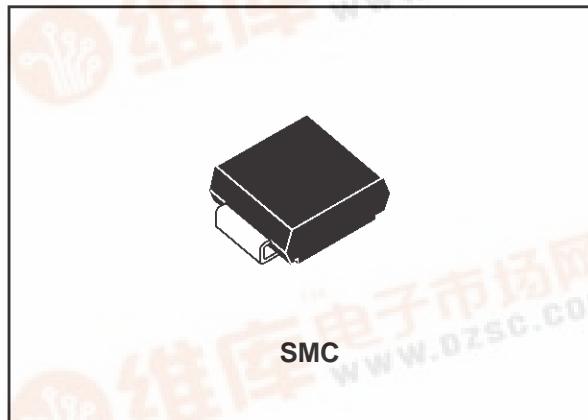
Application Specific Discretes

A.S.D.TM

DISCRETE SOLUTION FOR ISDN PROTECTION

FEATURES

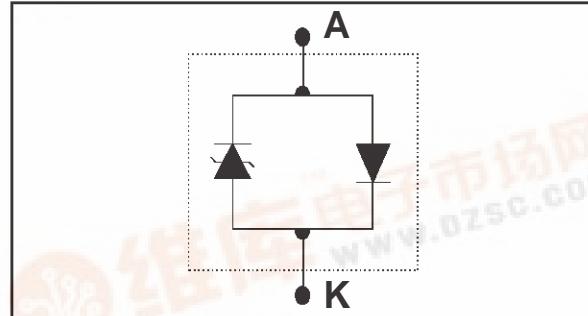
- UNIDIRECTIONAL CROWBAR PROTECTION.
- PEAK PULSE CURRENT: IPP = 75 A, 10/1000 μ s.
- HOLDING CURRENT = 150mA.
- BREAKDOWN VOLTAGE: SMTHDT58 = 58V. SMTHDT80 = 80V. SMTHDT120 = 120V.
- PACKAGES: SMTHDTxx = SURFACE MOUNT PACKAGE.

**DESCRIPTION: TRIBALANCED PROTECTION**

Dedicated protection devices for ISDN LINE CARD and high speed data telecom lines.

Used with the recommended configuration using 3 components, they will provide =

- Dual bidirectional protection, with fixed breakdown voltage in both common and differential modes.
- Low capacitances from lines to ground.
- Very good capacitance balance : $\Delta C = 30 \text{ pF}$.

FUNCTIONAL DIAGRAM.**ABSOLUTE RATINGS (limiting values) (-40°C ≤ T_{amb} ≤ +85°C)**

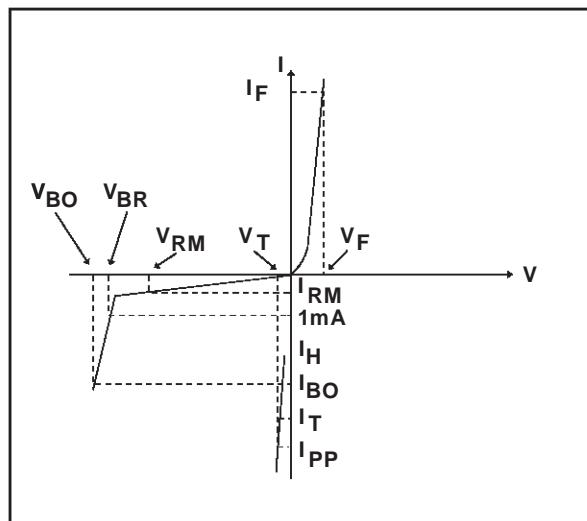
Symbol	Parameter	Value	Unit
I _{PP}	Peak pulse current	75 150	A
I _{TSM}	Non repetitive surge peak on-state current	30	A
di/dt	Critical rate of rise of on-state current	100	A/ μ s
dv/dt	Critical rate of rise of off-state voltage	5	KV/ μ s
T _{stg} T _j	Storage and operating junction temperature range	- 40 to + 150 + 150	°C °C

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-l)	Junction-leads Thermal Resistance	200	°C/W

SMTHDTxx

Symbol	Parameter
V_{RM}	Stand-off voltage
V_{BR}	Breakdown voltage
V_{BO}	Breakover voltage
I_H	Holding current
V_T	On-state voltage
V_F	Forward Voltage Drop
I_{BO}	Breakover current
I_{PP}	Peak pulse current
V_F	Forward Voltage Drop



PARAMETERS RELATED TO THE DIODE.

Parameter	Test conditions	Value	Unit
V_F	$I_F = 5A, T_P = 500 \mu s$	5	V

PARAMETERS RELATED TO THE PROTECTION TRISIL.

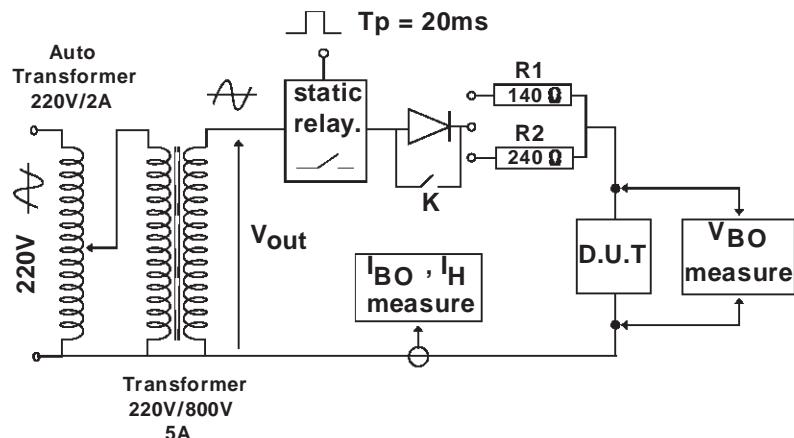
Types	$I_R @ V_{RM}$		$V_{BR} @ I_R$		V_{BO} max note1	I_{BO}		I_H min note1	VT max note2	C max note3
	μA	V	V	mA		V	mA			
SMTHDT58	10	56	58	1	80	150	800	150	5	400
SMTHDT80	10	68	80	1	120	150	800	150	5	250
SMTHDT120	10	102	120	1	180	150	800	150	5	200

All parameters tested at 25 °C, except where indicated.

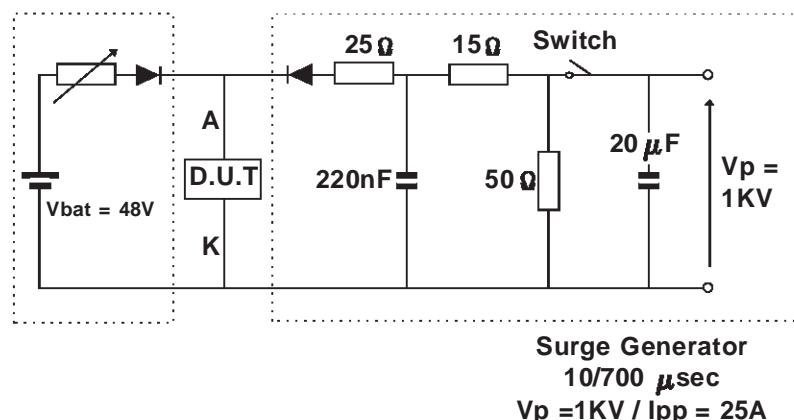
Note 1 : See the reference test circuit for I_H , I_{BO} and V_{BO} parameters.

Note 2 : Square pulse $T_P = 500 \mu s - I_T = 5A$.

Note 3 : $V_R = 1V, F = 1MHz$.

REFERENCE TEST CIRCUIT FOR I_H , I_{BO} and V_{BO} parameters :

TEST PROCEDURE :

- Pulse Test duration ($T_p = 20\text{ms}$):
 - For Bidirectional devices = Switch K is closed
 - For Unidirectional devices = Switch K is open.
- V_{out} Selection
 - Device with $V_{BR} \leq 150$ Volt
 - $V_{out} = 250$ VRMS, $R_1 = 140\Omega$.
 - Device with $V_{BR} \geq 150$ Volt
 - $V_{out} = 480$ VRMS, $R_2 = 240\Omega$.

FUNCTIONAL HOLDING CURRENT (I_H) TEST CIRCUIT = GO - NOGO TEST.


This is a GO-NOGO Test which allows to confirm the holding current (I_H) level in a functional test circuit. This test can be performed if the reference test circuit can't be implemented.

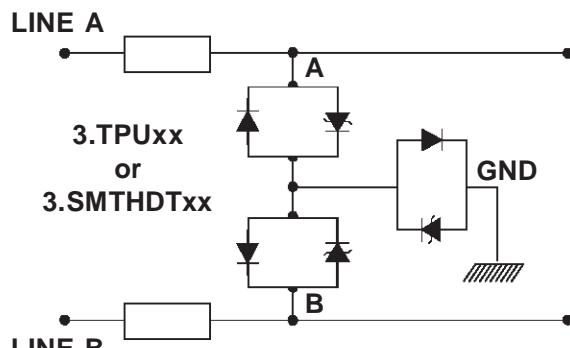
TEST PROCEDURE :

- 1) Adjust the current level at the I_H value by short circuiting the AK of the D.U.T.
- 2) Fire the D.U.T with a surge Current : $I_{pp} = 25A$, $10/700\mu\text{s}$.
- 3) The D.U.T will come back to the OFF-State within a duration of 50 ms max.

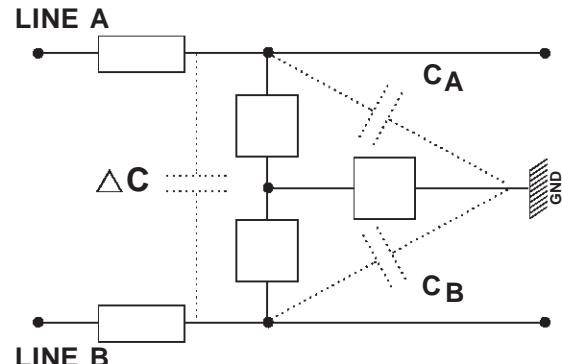
SMTHDTxx

APPLICATION NOTE

ISDN PROTECTION.



TRIPOLE PROTECTION



FULL BALANCED PROTECTION

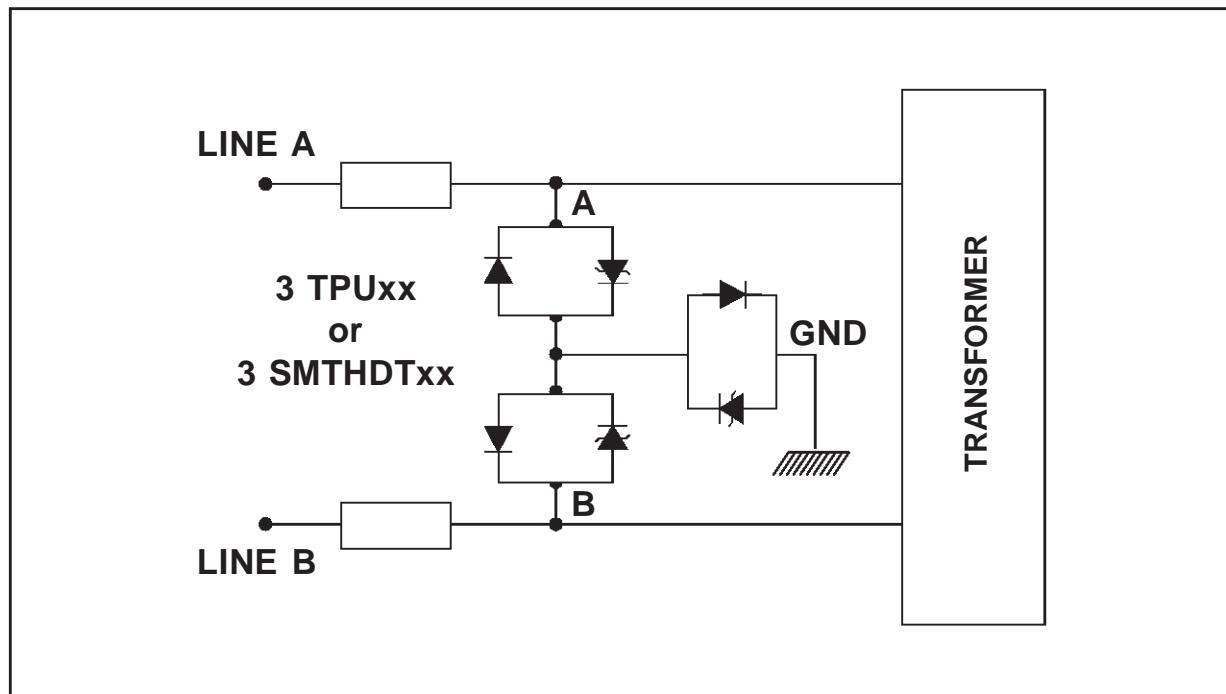
RECOMMENDED CONFIGURATION FOR TRIBALANCED PROTECTION MODE.

CAPACITANCE CHARACTERISTICS

Type	CONFIGURATION		C_A pF Max	C_B pF Max	ΔC pF Max
	LINE A	LINE B			
SMTHDT58	48	0	80	60	30
SMTHDT80	56	0	70	50	30
SMTHDT120	110	0	70	50	30

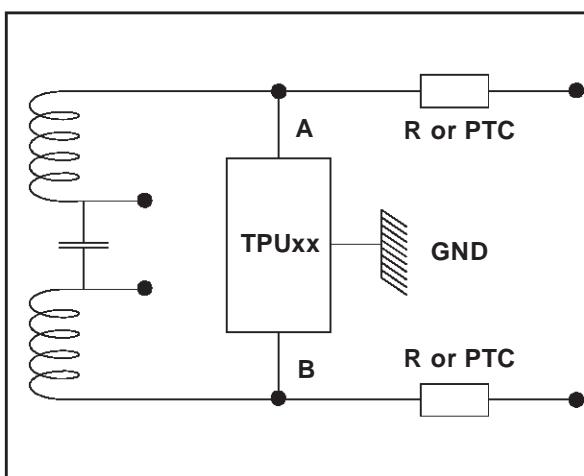
APPLICATION NOTE

Discrete ISDN Protection solution

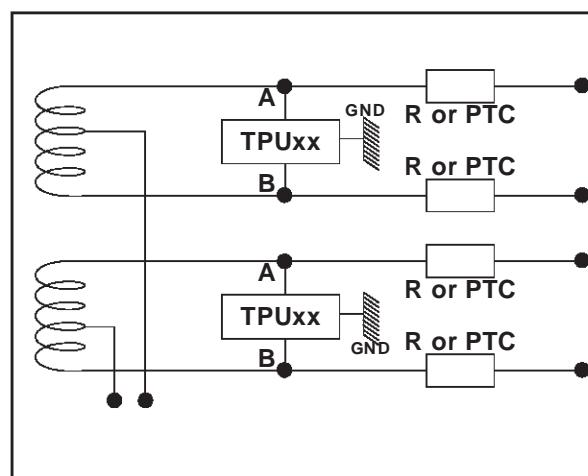


EQUIVALENT PROTECTION FUNCTION

U Interface Protection



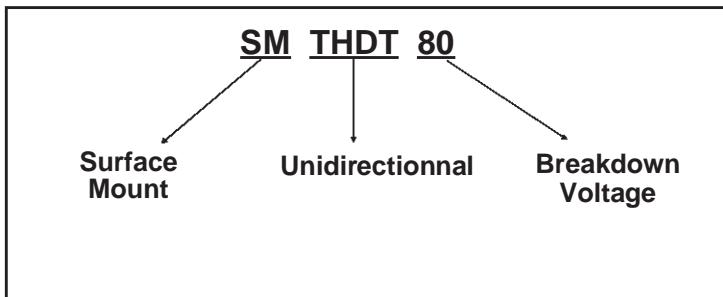
S Interface Protection



This topology assumes the same breakdown voltage level in positive and negative for differential or common mode surge.

SMTHDTxx

ORDER CODE



MARKING

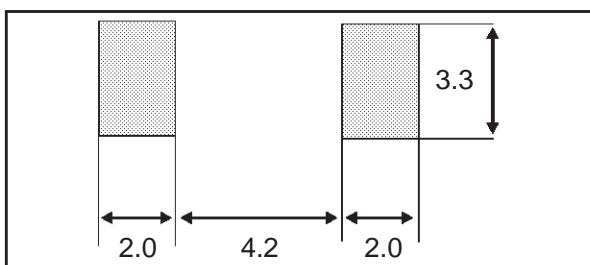
Package	Type	Marking
SMC	SMTHDT58 SMTHDT80 SMTHDT120	W01 W03 W05

PACKAGE MECHANICAL DATA

SMC

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.60	0.030	0.063

FOOTPRINT DIMENSIONS (in millimeters)



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied.

STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics

© 1999 STMicroelectronics - Printed in Italy - All rights reserved.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia

Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

<http://www.st.com>